L Number	Hits	Search Text	DB	Time stamp
1	2505256	semiconductor ic chip die (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/10 10:28
2	108014	leadframe (lead adj frame) paddle (die adj2 pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/10 10:29
3	115259	leadframe (lead adj frame) paddle ((chip dice die) adj2 pad)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/10
4	57547	(semiconductor ic chip die (integrated adj circuit)) same (leadframe (lead adj frame) paddle ((chip dice die) adj2 pad)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/04/10
5	2817	half adj6 (etching etched etch)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/10 10:31
6	586	<pre>((semiconductor ic chip die (integrated adj circuit)) same (leadframe (lead adj frame) paddle ((chip dice die) adj2 pad))) and (half adj6 (etching etched etch))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/10 10:31
7	1		USPAT	2004/04/10
8	1		USPAT	11:22 2004/04/10 11:22
9	1		USPAT	2004/04/10
10	1		USPAT	2004/04/10
11	1		USPAT	2004/04/10
12	1		USPAT	2004/04/10
13	1		USPAT	2004/04/10 11:24
14	1		USPAT	2004/04/10
15	1		USPAT	2004/04/10
16	1		USPAT	2004/04/10 11:24
17	1		USPAT	2004/04/10
18	1		USPAT	2004/04/10
19	1		USPAT	2004/04/10
20	1		USPAT	2004/04/10
21	1		USPAT	2004/04/10 11:26
22	1		USPAT	2004/04/10 11:26
23	1		USPAT	2004/04/10 11:26
24	1		USPAT	2004/04/10 11:27
25	1		USPAT	2004/04/10 11:27

26	1	USPAT	2004/04/10
20	1	OSIAI	11:27
27	1	USPAT	2004/04/10
	-	001111	11:27
28	1	USPAT	2004/04/10
			11:27
29	1	USPAT	2004/04/10
			11:27
30	1	USPAT	2004/04/10
			11:34
31	1	USPAT	2004/04/10
			11:34
32	1	USPAT	2004/04/10
			11:35
33	1	USPAT	2004/04/10
			11:35
34	1	USPAT	2004/04/10
	_		11:35
35	1	USPAT	2004/04/10
26			11:35
36	1	USPAT	2004/04/10
37	1	110DDM	11:35
31	1	USPAT	2004/04/10
38	1	USPAT	11:36 2004/04/10
30	1	USPAI	11:36
39	1	USPAT	2004/04/10
		ODIAL	11:36
40	1	USPAT	2004/04/10
	_	001111	11:36
41	1	USPAT	2004/04/10
			11:37
42	1	USPAT	2004/04/10
			11:37
43	1	USPAT	2004/04/10
			11:37
44	1	USPAT	2004/04/10
			11:37
45	1	USPAT	2004/04/10
	L		11:37

L	Hits	Search Text	DB	Time stamp
Number				
671	58	<pre>(aperture) with (half adj6 (etching etched etch))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/10 14:44